



Ordering Information:

Absolute Maximum Ratings $T_C = 25$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_{D@T_C=25}$	60	A
	$I_{D@T_C=75}$		



Single Pulse Avalanche Energy ($L=0.1\text{mH}, V_{GS}=10\text{V}, R_g=25\ \Omega, t_J=25\ \mu\text{s}$)	E_{AS}	66	mJ
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Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	1.5	$^{\circ}\text{C/W}$
Thermal resistance, junction - ambient	R_{thJA}	-	-	37	$^{\circ}\text{C/W}$
Soldering temperature, wave soldering for 10s	T_{sold}	-	-	265	$^{\circ}\text{C}$

Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	40			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	1.2		2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=40\text{V}, V_{GS}=0\text{V}$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20\text{V},$				



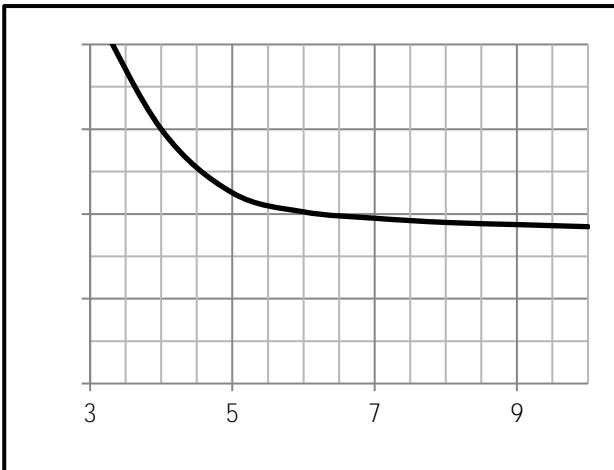


Fig.7 SOA Maximum Safe Operating Area

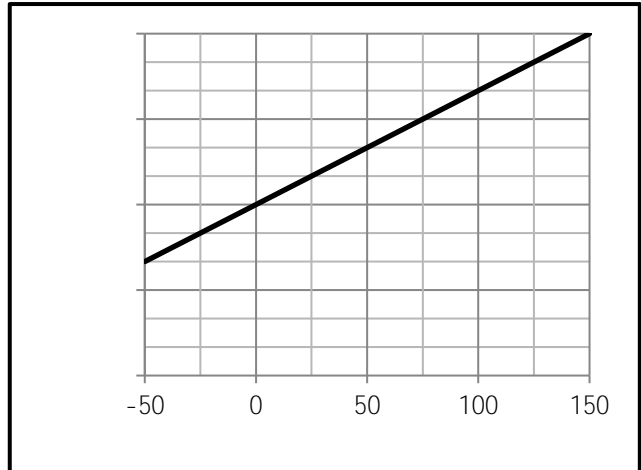
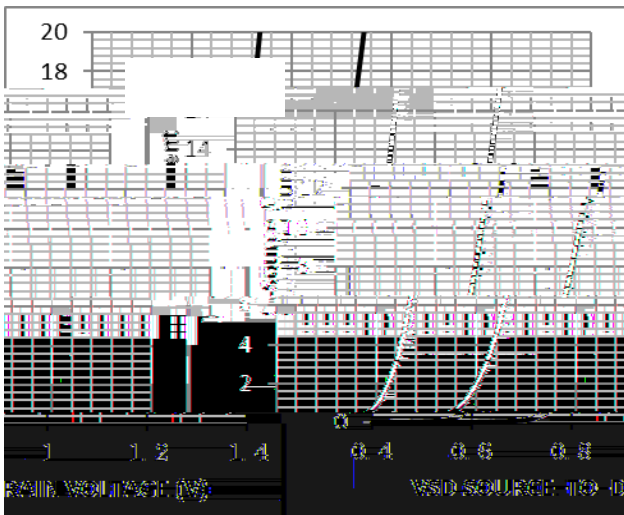
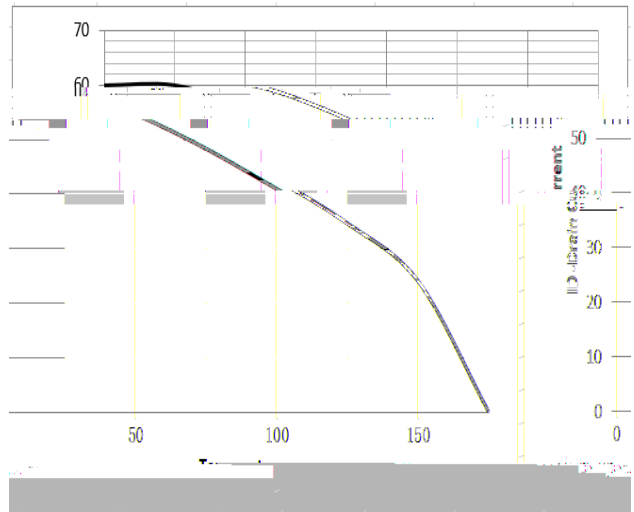


Fig.8 I_D -Junction Temperature







Dimensions DFN5x6

Unit mm

